



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*


Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-06-14
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
DVIULC6-4SC6Y	A0WB*YEWSOIA	A	ZS1A	2016-06-14
Amount		UoM	Unit type	ST ECOPACK Grade
14.00		mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nicke/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	2.9x1.625x1.175	6	gull wing	
Comment	Package: WB SOT 23 - 6L			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-17th December 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	AOWB*YEWSOIA					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	0.552	mg	supplier	die	Silicon (Si)	7440-21-3		0.482	mg	873188	34429
				supplier	metallization	Aluminium (Al)	7429-90-5		0.065	mg	117754	4643
				supplier	Passivation	Silicon Oxide	7631-86-9		0.005	mg	9058	357
Lead-frame	Other inorganic materials	6.584	mg	supplier	alloy	Copper (Cu)	7440-50-8		6.380	mg	969016	455714
				supplier	alloy	Iron (Fe)	7439-89-6		0.151	mg	22934	10786
				supplier	alloy	Phosphorus (P)	12185-10-3		0.002	mg	304	143
				supplier	alloy	Zinc (Zn)	7440-66-6		0.008	mg	1215	571
				supplier	metallization	Nickel (Ni)	7440-02-0		0.039	mg	5923	2786
				supplier	metallization	Palladium (Pd)	7440-05-3		0.003	mg	456	214
				supplier	metallization	Gold (Au)	7440-57-5		0.001	mg	152	71
Die Attach	Other inorganic materials	0.068	mg	supplier	glue	Epoxyde Bisphenol A Resin	25068-38-6		0.019	mg	279411	1359
				supplier	glue	Aromatic amine	Proprietary		0.003	mg	44118	214
				supplier	glue	Glycol ether ester	Proprietary		0.003	mg	44118	214
				supplier	glue	silica	60676-86-0		0.021	mg	308824	1500
				supplier	glue	Aluminium oxide	1344-28-1		0.022	mg	323529	1571
Bonding wire	Precious metals	0.114	mg	supplier	wire	Gold (Au)	7440-57-5		0.114	mg	1000000	8143
Encapsulation	Other inorganic materials	6.682	mg	supplier	mold compound	Silica, vitreous	60676-86-0		5.700	mg	853038	407143
				supplier	mold compound	phenolic resin	29690-82-2		0.233	mg	34870	16643
				supplier	mold compound	epoxy resin	25068-38-6		0.267	mg	39958	19071
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		0.134	mg	20054	9571
				supplier	mold compound	carbon black	1333-86-4		0.014	mg	2095	1000
				supplier	mold compound	Zinc hydroxide	20427-58-1		0.067	mg	10027	4786
				supplier	mold compound	Magnesium hydroxide	1309-42-8		0.267	mg	39958	19071